

IN THE SPECIFICATION:

Please substitute the following marked up paragraph(s) for the paragraph(s) now appearing in the currently filed specification:

On Page 4, the paragraph beginning at line 3:

B₁ Next, as shown in Fig. ~~25D~~26A, a seed copper film 306 is formed on the barrier film 305 to a predetermined thickness by well-known sputterings.

On Page 4, the paragraph beginning at line 6:

B₂ Then, as shown in Fig. ~~25E~~26B, a copper film 307 is formed so as to bury the contact holes CH and the grooves M by copper. The copper film 307 is formed by the process of plating, CVD, sputtering, etc.

On Page 4, the paragraph beginning at line 10:

B₃ Next, as shown in Fig. ~~25F~~26C, the excess copper film 307 and barrier film 305 on the interlayer insulation film 302 are removed by CMP for flattening.

On Page 29, the paragraph beginning at line 18:

B₄ Fig. ~~2D~~2A and ~~2E~~2B are views of the steps continuing from Fig. 1A to 1C, where Fig. ~~2D~~2A shows the step of forming a copper film as a seed film, while Fig. ~~2E~~2B shows the step of forming a copper film;

On Page 29, the paragraph beginning at line 22:

B₅ Fig. ~~3F~~3A and ~~3G~~3B are views of the steps continuing from Fig. ~~2D~~2A and ~~2E~~2B, where Fig. ~~3F~~3A shows the step of anodic oxidation of the copper film, while Fig. ~~3G~~3B shows the step of forming a chelate film;

On Page 30, the paragraph beginning at line 1:

B6 Fig. 4H-4A and 4I-4B are views of the steps continuing from Fig. 3F-3A and 3G-3B, where Fig. 4H-4A shows the step of removing projecting portions of the chelate film, while Fig. 4I-4B shows the step of re-forming a chelate film;

On Page 30, the paragraph beginning at line 5:

B7 Fig. 5J-5A to 5L-5C are views of the steps continued from Fig. 4H-4A and 4I-4B, where Fig. 5J-5A shows the step of flattening the copper film, Fig. 5K-5B shows the step of removing excess copper film, and Fig. 5L-5C shows the step of exposing the barrier film;

On Page 32, the paragraph beginning at line 16:

B8 Fig. 26D-26A to 26F-26C are views of the steps continuing from Fig. 25A to 25C, where Fig. 26D-26A shows the step of forming a seed film, Fig. 26E-26B shows the step of forming an interconnection layer, and Fig. 26F-26C shows the step of forming interconnections;
